

EFFTRONICS SYSTEMS PVT. LTD.

Plot No-4, IT Park, Mangalagiri-522 503, Guntur, AP, INDIA +91 (8645) 666777 | info@efftronics.com | www.efftronics.com

Memorandum Of Understanding

Between

Lakireddy Bali Reddy College of Engineering, Mylavaram

And

Efftronics Systems Pvt Ltd

This Agreement made and entered into on 26-Mar-2024 between Lakireddy Bali Reddy College of Engineering, Mylavaram and Efftronics Systems Pvt Ltd (here in after called Efftronics) situated at IT Park, Mangalagiri. This MOU shall be valid for 1 years from the date and each party shall be at full liberty to terminate the collaboration with a notice period of 3 months.

Objectives of the MOU:

The objective of this Memorandum of Understanding is:

A. To promote interaction between Lakireddy Bali Reddy College of Engineering, Mylavaram and Efftronics in mutually beneficial areas.

B. To provide a formal basis for initiating interaction between Lakireddy Bali Reddy College of Engineering, Mylavaram and Efftronics.

Proposed Modes of Collaboration:

Lakireddy Bali Reddy College of Engineering, Mylavaram and Efftronics propose to collaborate through.

- 1. Exchanging of expertise by means of Guest Lectures, Technical Seminars, Workshops and other events (during regular working days) for the benefit of the faculty and students.
- 2. Permitting students for One-day Industrial Visit.
- 3. Allowing faculty & Staff for industrial training.
- 4. Permitting Practical training to students.
- 5. Attending campus recruitment where the intake depends up on the clearance of all the rounds by the candidate in selection process.

<u>Note:</u> All the above modes will be decided upon mutual consent based on Availability, Work Schedules and Manpower of Company.

Date of Agreement: 26-Mar-2024

With Regards

For Efftronics Systems Pvt. Ltd.,

Lakireddy Bali Reddy College of Engineering, Mylavaram

(SPURTHI D)

HR MANAGER

(Dr. K. APPA RAO) 26/03/2014

PRINCIPAL

CIN: U51909AP1987PTC007554 | GST: 37AAACE4879Q1ZT

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